

Form 1449 (Modified)	Atty Docket No. NSC1P131X3	Application No.: 10/707,208
<b>Information Disclosure Statement By Applicant</b>	Applicant: Patwardhan et al.	
(Use Several Sheets if Necessary)	Filing Date 11/26/03	Group Not Yet Assigned

#### U.S. Patent Documents

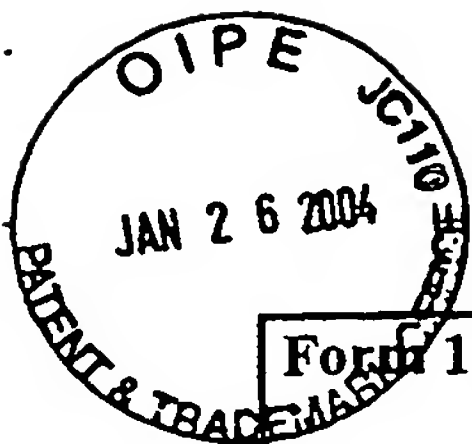
Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub- class	Filing Date
* W	A	5,214,308	05/93	Nishiguchi et al.			
*	B	5,495,439	02/96	Morihara			
*	C	5,668,059	09/97	Christie et al.			
*	D	5,895,976	04/00	Morrell et al.			
*	E	5,872,633	02/99	Holzapfel et al.			
*	F	5,953,623	09/99	Boyko et al.			
*	G	6,060,373	05/00	Saitoh			
*	H	6,063,647	05/00	Chen et al.			
*	I	6,071,757	06/00	Fogal et al.			
*	J	6,121,689	09/00	Capote et al.			
*	K	6,130,473	10/00	Mostafazadeh et al.			
*	L	6,190,940	2/01	DeFelice et al.			
*	M	6,245,595	06/01	Nguyen et al.			
*	N	6,258,626	7/01	Wang et al.			
*	O	6,307,269	10/01	Akiyama et al.			
*	P	6,391,683	05/02	Chiu et al.			
*	Q	6,486,562	11/02	Kato			
*	R	6,507,118	01/03	Schueller			

#### U.S. Published Patent Documents

Examiner Initial	No.	Publication No.	Date	Name	Class	Sub- class	Filing Date
* W	S	20030087475	5/2003	Sterrett et al.			
*	T	20020171152	11/2002	Miyazaki			
*	U	20020109228	8/2002	Buchwalter et al.			
*	V	20030001283	1/2003	Kumamoto			

Examiner <i>Uthi Trih</i>	Date Considered <i>4/2/05</i>
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Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

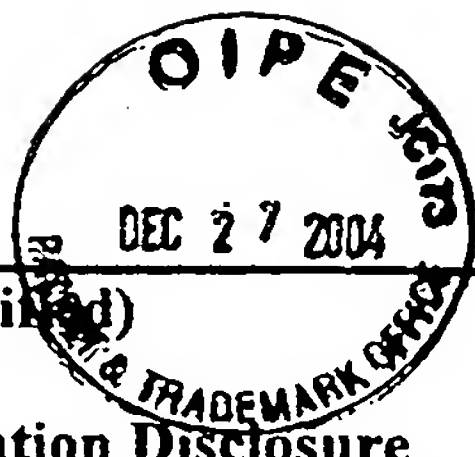


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Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
*	W	Kulicke & Soffa, "Flip Chip Products, Polymer Collar Wafer Level Package; Achieve Maximum Reliability for Wafer Level Packages!", December 7, 2001, <a href="http://www.kns.com">www.kns.com</a>
*	X	Kulicke & Soffa, "Flip Chip Division, Polymer Collar Wafer Level Package; See the Polymer Collar WLP difference!", December 7, 2001, <a href="http://www.kns.com">www.kns.com</a>
*	Y	"Fundamentals of Microsystem Packaging", Rao R. Tummala, Chapters 2, 10, and 17, (May 8, 2001) McGraw-Hill Professional Publishing; ISBN: 0071371699
*	Z	"Chip Scale Package: Design, Materials, Process, Reliability, and Applications", John H. Lau and S.W. Ricky Lee, Chapter 1, Pages 1-41, (February 28, 1999) McGraw-Hill Professional Publishing; ISBN: 0070383049.
WZ	AA	"All Dressed Up and Nowhere to Go", Bogatin, Eric; Contributing Editor, May 1, 2002, Semiconductor, Downloaded on 12/23/2003 from <a href="http://www.reed-electronics.com/semiconductor/index.asp?layout=article&amp;articleid=CA213812&amp;rid=0&amp;rme=0&amp;cfd=1">http://www.reed-electronics.com/semiconductor/index.asp?layout=article&amp;articleid=CA213812&amp;rid=0&amp;rme=0&amp;cfd=1</a> , 2 pages ✓
WZ	BB	Kulicke & Soffa, "Polymer Collar WLP™, Wafer Level Package Family" ©2002, 2 pages. ✓ <a href="http://www.kns.com/prodserv/PDFS/FCD/polymer_collar.pdf">http://www.kns.com/prodserv/PDFS/FCD/polymer_collar.pdf</a>
WZ	CC	"Polymer Collar WLP™ - A New Wafer Level Package for Improved Solder Joint Reliability", Barrett et al., Kulicke & Soffa - Flip Chip Division, Downloaded from: <a href="http://www.kns.com/resources/articles/PolymerCollar.pdf">http://www.kns.com/resources/articles/PolymerCollar.pdf</a> , 9 Pages ✓
WZ	DD	Kulicke & Soffa, "Presenting Polymer Collar WLP™ - A New Wafer Level Package for Improved Solder Joint Reliability", © 2002, Downloaded from: <a href="http://www.kns.com/prodserv/flipchip/pdf/PC_ad.pdf">http://www.kns.com/prodserv/flipchip/pdf/PC_ad.pdf</a> , 1 page. ✓
Examiner	Vikram Mishra	
Date Considered	4/7/05	

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



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	<b>Applicant:</b> Patwardhan et al.	<b>Group</b> 2814
	<b>Filing Date</b> November 26, 2003	

#### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
WZ	A	5,925,936	07/20/99	Yamaji			02/26/97
	B	6,171,887	01/09/01	Yamaji			05/04/99
	C	2002/0003299 A1	01/10/02	Nakamura et al.			03/11/98
	D						
	E						
	F						
	G						
	H						
	I						

#### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	J							
	K							
	L							
	M							
	N							

#### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	O	
	P	
	Q	
Examiner	Vikhi Tripathi	
	Date Considered	4/7/05

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#### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A	6,455,920	09/24/02	Fukasawa, et al.	257	620	09/25/98
	B						
	C						
	D						
	E						
	F						
	G						
	H						
	I						

#### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	J							
	K							
	L							
	M							
	N							

#### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	O	
	P	
	Q	
Examiner		
	Date Considered	4/7/05

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	Applicant: <b>PATWARDHAN et al.</b>	
	Filing Date <b>11-26-2003</b>	Group <b>2814</b>

#### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub- class	Filing Date
	A	2003/0218258	11-27-2003	CHARLES et al.			
	B						
	C						
	D						
	E						
	F						
	G						
	H						
	I						

#### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub- class	Translation	
							Yes	No
	J							
	K							
	L							
	M							
	N							

#### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	O	
	P	
	Q	
Examiner	Date Considered <b>4/7/05</b>	

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